

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): An apparatus comprising:

a device chip including substrate and at least one circuit element fabricated on the substrate;

a cap over said device chip, said cap including a gasket having an inner surface and an outer surface;

a bonding agent bonding said cap to said device chip ~~defining to define~~ a hermetically sealed cavity ~~having an inner surface and an outer surface~~; and

caulking agent at least partially surrounding said bonding agent ~~reinforcing to reinforce~~ the hermetically seal sealed cavity, said caulking agent surrounding said bonding agent at at least one of two surfaces the inner surface of the gasket, ~~the two surfaces being the inner surface and the outer surface~~.

Claim 2 (original): The apparatus recited in claim 1 wherein the bonding agent comprises gold.

Claim 3 (original): The apparatus recited in claim 1 wherein the caulking agent is selected from a group consisting of amorphous fluorocarbon polymer, polyimide materials, and benzocyclobutene (BCB) based materials.

Claim 4 (original): The apparatus recited in claim 1 wherein the circuit element comprises a resonator.

Claim 5 (canceled).

Claim 6 (previously presented): The apparatus recited in claim 1 wherein the caulking agent surrounds at least a portion of the cap.

Claim 7 (canceled).

Claim 8 (canceled).

Claim 9 (original): The apparatus recited in claim 1 comprising multiple layers of the caulking agent.

Claim 10 (original): The apparatus recited in claim 9 wherein the multiple layers of the caulking agent comprises layers having different caulking material relative to other layers of the caulking agent.

Claim 11 (currently amended): The apparatus recited in claim [[8]] 9 wherein the multiple layers of the caulking agent comprises layers having the same caulking material relative to other layers of the caulking agent.

Claim 12 (previously withdrawn): A method of manufacturing an apparatus, the method comprising:

fabricating a device chip including a substrate and at least one circuit element on the substrate;

fabricating a cap;

bonding the cap on the device chip such that a sealed cavity is formed; and

reflowing caulking agent further sealing the cavity.

Claim 13 (previously withdrawn): The method recited in claim 12 wherein the step of fabricating the device chip includes a step of depositing caulking agent on the device chip.

Claim 14 (previously withdrawn): The method recited in claim 12 wherein the step of fabricating the cap includes a step of depositing caulking agent on the cap.

Claim 15 (previously withdrawn): The method recited in claim 12 wherein the cap is bonded to the device chip using bonding agent comprising gold.

Claim 16 (previously withdrawn): The method recited in claim 12 wherein the caulking agent is selected from a group consisting of amorphous fluorocarbon polymer, polyimide materials, and benzocyclobutene (BCB) based materials.

Claim 17 (previously withdrawn): The method recited in claim 12 wherein the circuit element comprises a resonator.

- Claim 18 (previously withdrawn): The method recited in claim 12 wherein the caulking agent caulks at least a portion of the cap.
- Claim 19 (previously withdrawn): The method recited in claim 12 wherein the cap includes a gasket that is caulked by the caulking agent.
- Claim 20 (currently amended): The apparatus recited in claim 1 wherein the caulking agent surrounds said bonding agent at both the inner and the outer surfaces of the gasket.
- Claim 21 (previously presented): The apparatus recited in claim 1 wherein the caulking agent extends from said cap to said device chip.
- Claim 22 (previously presented): The apparatus recited in claim 1 wherein the caulking agent is adjacent to said bonding agent.
- Claim 23 (currently amended): The apparatus recited in claim 1 wherein the caulking agent is separated from said bonding agent by open space prior to bonding said cap to said device chip.